

Fox Electronics Headquarters
5570 Enterprise Parkway
Fort Myers, FL 33905 USA
Tel: 888-GET-2-FOX
Outside US: +239.693.0099
Fax: +1.239.693.1554

Fox Electronics EMEA
9 Alderson Drive
Stretton
Burton upon Trent
Staffordshire
DE13 0QQ
Tel: +44.1283.588153

Fox Electronics Asia
21/F, Cheong Sun Tower
118 Wing Lok Street
Sheung Wan, Hong Kong
Tel: +852.2854.4285
Fax: +852.2854.4282

Fox Electronics Singapore
61 Kaki Bukit Ave 1 #04-38
Shun Li Industrial Park
417943
Tel: +65.6844798

Fox Electronics Japan
3-28-6-1A Yoyogi
Shibuya-ku, Tokyo 151
Japan
Tel: +81.3.3374.2079
Fax: +83.3.3377.5221

Materials Declaration

Company Name : Fox Electronics

**Address : 5570 Enterprise Parkway
: Ft Myers FL 33905**

Phone : 239-690-2238

Fax : 239-690-3438

E-mail : brucec@foxonline.com

Completed by Bruce Clark

Date : February 20, 2007

Product Family : 4.6x12.5x3.7mm Plastic Package Crystal (FPXLF Rev. C)

*Revised 12/18/07

** Added 3/25/2011

	Material Name	Component	Content (mg)	Content (w t %)	(CAS Number)
Cover	Nickel Silver	Nickel (Ni)	16.950	5.258%	7440-02-0
		Copper (Cu)	59.878	18.574%	7440-50-8
		Iron (Fe)	0.267	0.083%	7439-89-6
		Manganese (Mn)	0.565	0.175%	7439-96-5
		Zinc (Zn)	20.219	6.272%	7440-66-6
	Nickel Plating	Nickel (Ni)	7.497	2.326%	7440-02-0
Base	Alloy 42	Iron (Fe)	9.564	2.967%	7439-89-6
		Nickel (Ni)	6.926	2.148%	7440-02-0
	Glass	Silicon Dioxide (SiO ₂)	10.750	3.335%	14808-60-7
	Kovar	Iron (Fe)	3.666	1.137%	7439-89-6
		Nickel (Ni)	1.972	0.612%	7440-02-0
		Cobalt (Co)	1.156	0.359%	7440-48-4
	Nickel Plating	Nickel (Ni)	0.702	0.218%	7440-02-0
	Solder Plating	Tin (Sn)	0.713	0.2212%	7440-31-5
		Lead (Pb)**	5.182	1.607%	7439-92-1
Plastic Mold	Epoxy Molding Compound	LCP	122.5000	37.999%	
Leadframe	Brass	Copper (Cu)	29.106	9.028%	7440-50-8
		Zinc (Zn)	14.994	4.65%	7440-66-6
	Copper Plating	Copper (Cu)	0.776	0.24%	7440-50-8
	Termination Plating	*Matte Tin (Sn)	3.274	1.016%	7440-31-5
Crystal	Crystal	Silicon Dioxide (SiO ₂)	3.03	0.94%	14808-60-7
	Electrode	Silver (Ag)	0.050	0.0155%	7440-22-4
		Chromium (Cr)	0.004	0.0012%	7440-47-3
	Solder	Tin (Sn)	0.139	0.0431%	7440-31-5
		Silver (Ag)	0.05000	0.015510%	7440-22-4
		Lead (Pb)**	2.450000	0.759973%	7439-92-1
TOTAL			322.38	100.00%	

** Covered by Exemption 7(a) - Lead in high melting temperature solders(i.e., lead-based alloys containing 85% by weight or more lead)